

PCN Number:	20140930001		PCN Date:	10/01/2014										
Title:	Datasheet changes, Die revision, and Mount Compound Change for UCD3138064 family of devices													
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services									
Proposed 1st Ship Date:	01/01/2015		Estimated Sample Availability:	Date provided at sample request										
Change Type:														
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site									
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material									
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process									
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site									
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials									
				<input type="checkbox"/>	Wafer Fab Process									
PCN Details														
Description of Change:														
Texas Instruments is pleased to announce that the family of UCD3138064 devices will undergo a few datasheet changes, a minor Die revision, and a mount compound change:														
<table border="1"> <thead> <tr> <th>Pkg</th> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td>Die Rev</td> <td>A3</td> <td>A4</td> </tr> <tr> <td>Mount Compound</td> <td>4207768</td> <td>4207123</td> </tr> </tbody> </table>						Pkg	From	To	Die Rev	A3	A4	Mount Compound	4207768	4207123
Pkg	From	To												
Die Rev	A3	A4												
Mount Compound	4207768	4207123												
Datasheet Changes:														
Changes from Revision A (February 2014) to Revision B					Page									
<ul style="list-style-type: none"> Added <i>Pin Configuration and Functions</i> section, <i>Handling Rating</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i>, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section 					<u>1</u>									
<ul style="list-style-type: none"> Added 40-pin RMH QFN package option (global), 					<u>1</u>									
The datasheet number will be changing:														
Device Family	Change From:		Change To:											
UCD3138064	SLUSB72A		SLUSB72B											
These changes may be reviewed at the datasheet links provided. http://www.ti.com/general/docs/lit/getliterature.tsp?genericPartNumber=ucd3138064&fileType=pdf														
Reason for Change:														
Die rev for product performance. Mount Compound change for Assembly Materials standardization.														
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):														
None														

Changes to product identification resulting from this PCN:

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 / 260C/1 YEAR SEAL DT
 MSL 1 / 235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) **REV: (A)** 0033317
 (20L) CS0: SHE (21L) CCO:USA
 (22L) AS0: MLA (23L) ACO: MYS

Die Rev Marking:

Current= A3

New= A

Product Affected:

UCD3138064RGCR	UCD3138064RGZR	UCD3138064RMHR	UCD3138064RMHT
UCD3138064RGCT	UCD3138064RGZT		

Reference Qualification Data: Approved September 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: UCD3138064RGC (MSL3-260C)

Package Construction Details

Assembly Site:	Clark A/T	Mold Compound:	4208625
# Pins-Designator, Family:	64-RGC, VQFN	Mount Compound:	4207123
Lead Finish:	NiPdAu	Bond Wire:	0.96 Mil Dia., Au

Qualification: Plan **Test Results**

Reliability Test	Conditions	Sample Size / Fail
Electrical Characterization	Full Temperature	Pass
**T/C -65C/150C	-65C/+150C (500 Cycles)	77/0

Notes: **Tests require preconditioning sequence: MSL3-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com